



Surface Mount Glass Passivated Rectifier

Features

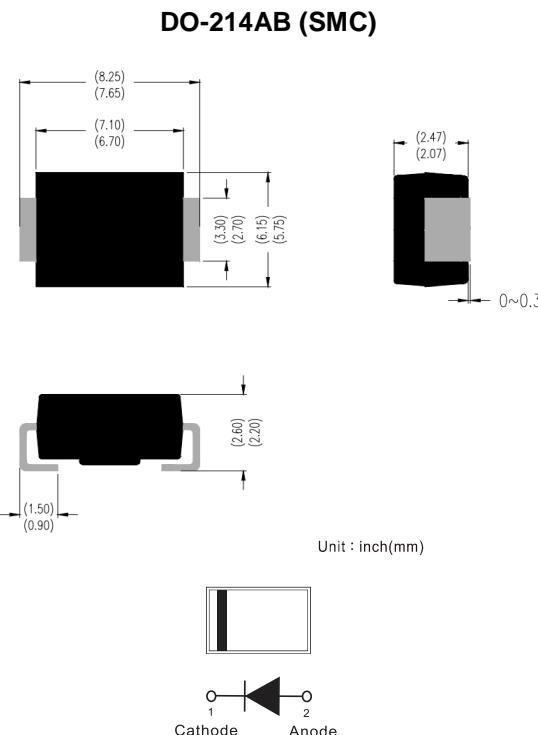
- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Typical Applications

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.

Mechanical Data

- Package: DO-214AB (SMC)
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Polarity: Color band denotes the cathode end



■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	S10A	S10B	S10D	S10G	S10J	S10K	S10M
Maximum Repetitive peak reverse voltage	V _{RRM}	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V	35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V _{DC}	V	50	100	200	400	600	800	1000
Average Rectified Output Current @60Hz sine wave, Resistance load, TL (FIG.1)	I _O	A				10			
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, T _j =25°C	I _{FSM}	A				200			
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, T _j =25°C						400			
Current squared time @1ms≤t≤8.3ms T _j =25°C, Rating of per diode	I ² t	A ² s				166			
Typical junction capacitance @Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	C _j	pF				55			
Storage Temperature	T _{stg}	°C				-55 ~ +150			
Junction Temperature	T _j	°C				-55 ~ +150			



■ Electrical Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	S10A	S10B	S10D	S10G	S10J	S10K	S10M
Maximum instantaneous forward voltage drop per diode	VF	V	IFM=10A							1.1
Maximum DC reverse current at rated DC blocking voltage per diode	IR	μA	$T_j=25^\circ\text{C}$							5
			$T_j=125^\circ\text{C}$							100

■ Thermal Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	S10A	S10B	S10D	S10G	S10J	S10K	S10M
Typical Thermal resistance	R _{θJ-A(1)}	$^\circ\text{C}/\text{W}$							50
	R _{θJ-L(1)}								10
	R _{θJ-C(1)}								8

Note(1)

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.6" x 0.6" (16 mm x 16 mm) copper pad areas

■ Characteristics(Typical)

FIG.1: Io-TL Curve

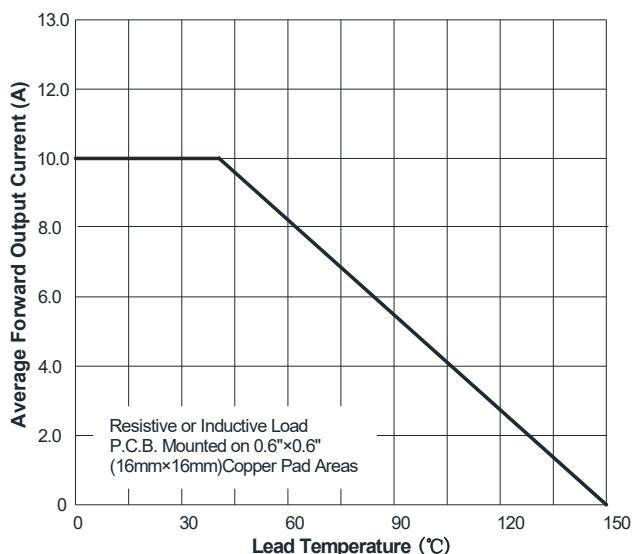


FIG.2: Forward Surge Current Capability

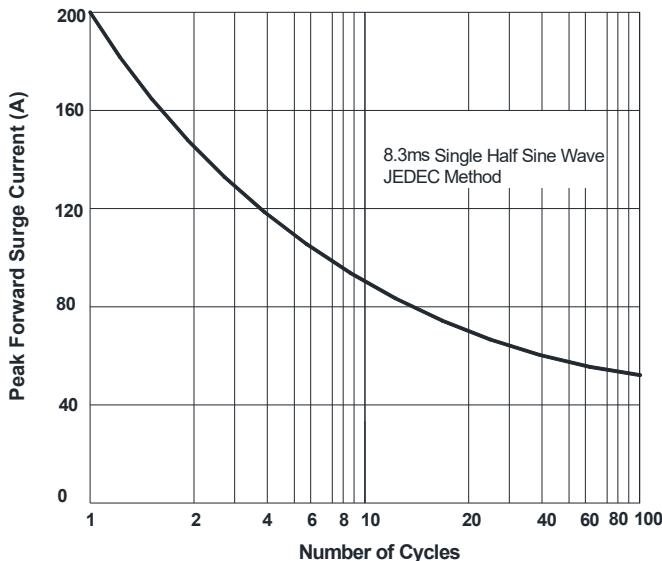


FIG.3: Typical Forward Voltage

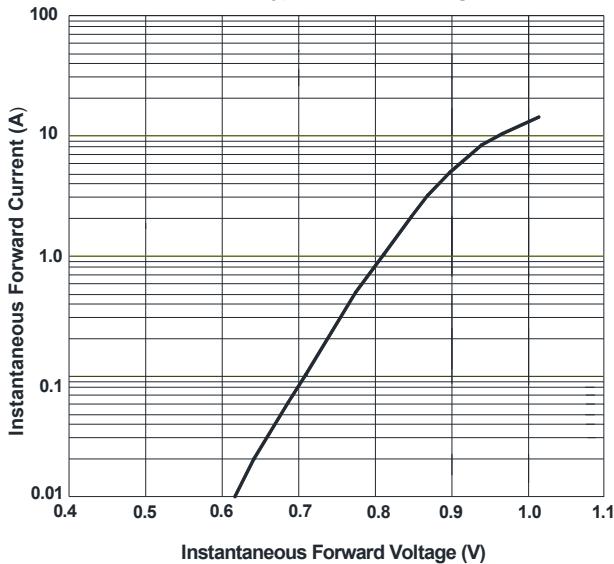


FIG.4: Typical Reverse Characteristics

